

| Part Name | Component Dimensions |  |  |  | Cable Dimensions |  |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  | L | A | B | K | D | E | F | $\mathrm{J} \pm 0.5$ |
|  | $\max$ | $\min$ | $\min$ | $\min$ | $\max$ | $\min$ | $\min$ | $(\mathrm{~J} \pm 0.02)$ |
| B-058-02-02 | 22.5 | 6.5 | 7.4 | 400 | 6.5 | 3.5 | 3.2 | 7 |
|  | $(0.885)$ | $(0.255)$ | $(0.291)$ | $(15.75)$ | $(0.255)$ | $(0.140)$ | $(0.125)$ | $(0.275)$ |

## MATERIAL

1. INSULATION SLEEVE: Heat-shrinkable, radiation cross-linked modified polyvinylidene fluoride. Transparent blue.
2. SOLDER PREFORM WITH FLUX:

SOLDER: TYPE Sn63 per ANSI J-STD-006.
FLUX: TYPE ROM1 per ANSI J-STD-004.
3. \& 4. MELTABLE RINGS: Thermally stabilized thermoplastic. Color: clear.
5. GROUND LEAD: RAYCHEM 55A0111-18 in accordance with MIL-W-22759/32 18 AWG. Stranded tin plated copper wire.

## APPLICATION

1. These parts are designed to provide an environment protected shield termination on cables rated for $125^{\circ} \mathrm{C}$ minimum, meeting the dimensional criteria listed and having bare or tin silver plated copper shields.
2. Temperature range: $-55^{\circ} \mathrm{C}$ to $+150^{\circ} \mathrm{C}$.
3. Install using TE Connectivity/Raychem-approved convection or infrared tools in accordance with Raychem installation procedure RPIP-709-00.

For best results, prepare the cable as shown:


| C |  |  | Raychem THERMOFIT DEVICES | SOLDERSLEEVE* DEVICE WITH PRE-INSTALLED LEAD |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Unless otherwise specified dimensions are in millimeters. [Inches dimensions are shown in brackets] |  |  |  | DOCUMENT NO.: ${ }^{\text {B-058-02-02 }}$ |  |  |
| $\begin{aligned} & \hline \text { TOLERANCES: } \\ & 0.00 \mathrm{~N} / \mathrm{A} \\ & 0.0 \mathrm{~N} / \mathrm{A} \\ & 0 \mathrm{~N} / \mathrm{A} \\ & \hline \end{aligned}$ | ANGLES: N/A ROUGHNESS IN MICRON |  | TE Connectivity reserves the right to amend this drawing at any time. Users should evaluate the suitability of the product for their application. | REV: 5 | DATE : | -APR-2020 |
| $\begin{gathered} \hline \text { DRAWN BY: } \\ \text { R. MAPAI } \\ \hline \end{gathered}$ |  | $\begin{aligned} & \hline \text { DATE: } \\ & \text { 16-OCT-98 } \\ & \hline \end{aligned}$ | $\begin{aligned} & \hline \text { ECO: } \\ & \text { ECO-20-005247 } \end{aligned}$ | $\begin{array}{ll} \hline \text { SCALE: } & \\ & \text { NTS } \\ \hline \end{array}$ | $\begin{array}{r} \hline \text { SIZE: } \\ \text { A } \end{array}$ | SHEET: 1 of 1 |

© 2020 TE Connectivity Ltd. Family of Companies. All Rights Reserved.
If this document is printed it becomes uncontrolled. Check for the latest revision.
*TE Connectivity, TE connectivity (logo), Raychem, THERMOFIT, SolderSleeve are trademarks

